

IN THE SPECIFICATION

Please amend the title to the following:

B2

**"LAYERED CIRCUIT BOARDS, ~~AND METHODS OF PRODUCTION~~ AND USES  
THEREOF"**

Please amend the abstract to the following:

B3

Compositions and methods are provided whereby printed wiring boards may be produced that comprise a) a substrate layer, and b) a solid, substantially planar optical wave-guide laminated onto the substrate layer. The printed wiring board further comprises at least one of a laminating material or a cladding material coupled to the wave-guide, and at least one additional layer coupled to the laminating material or the cladding material. Methods are also provided whereby an electronic component is produced that comprises a) providing a substrate layer; b) providing a solid, substantially planar optical wave-guide; and c) laminating the solid, substantially planar optical wave-guide onto the substrate layer.